

Abstract

[Object] A method for processing a substrate and an apparatus for processing a substrate are provided, where a substrate can be prevented from being damaged during conveyance of the substrate, including turning over of the substrate, and the apparatus for processing a substrate having this mechanism for conveying a substrate is miniaturized, so that the area for installment can be reduced.

[Means for Achieving Object] An apparatus for processing a substrate which divides a mother substrate into unit substrates is provided with a scribing portion 3 for drawing a scribe line on a mother substrate, a breaking portion 4 for breaking a mother substrate along the formed scribe line, and a portion for conveying a substrate 2 for conveying a mother substrate or a unit substrate at least between the above described respective portions, wherein portion for conveying a substrate 2 has a number of rotational supports 51 and 73 with a suction surface for sucking and holding each substrate from a main surface, rotational supports 51 and 73 have rotational axes 52 and 72, respectively, as well as means for respectively sucking and rotating a substrate which rotates substrates around rotational axes 52 and 72, approximately simultaneously in a state where the substrates are sucked and held in such a manner that at least two main surfaces of each substrate are turned over in the upward and downward direction.